

# **Product Change Notification - RMES-16DZWG089**

Date:

13 Sep 2019

**Product Category:** 

Successive Approximation Register (SAR) A/D Converters

**Affected CPNs:** 



**Notification subject:** 

CCB 2929.001 Final Notice: Qualification of NSEB as a new assembly site for selected products available in 10L MSOP (3x3mm) package.

**Notification text:** 

**PCN Status:** 

Final notification

**PCN Type:** 

Manufacturing Change

**Microchip Parts Affected:** 

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** 

Qualification of NSEB as a new assembly site for selected products available in 10L MSOP (3x3mm) package.

Pre Change:

Assembled at ANAP site using 8290 die attach and G700K mold compound material.

**Post Change:** 

Assembled at NSEB site using 8200T die attach and G600 mold compound material.

**Pre and Post Change Summary:** 

	Pre Change	Post Change					
Assembly Site	Amkor Technology Philippines	UTAC Thai Limited					
	(ANAP)	(NSEB)					
Wire material	Au	Au					
Die attach material	8290	8200T					
Molding compound material	G700K	G600					
Lead frame material	C7025	C7025					

## Impacts to Data Sheet:

None

**Change Impact:** 

None

Reason for Change:

To improve on time delivery performance by qualifying NSEB as a new assembly site.

**Change Implementation Status:** 

In Progress

**Estimated First Ship Date:** 

October 13, 2019 (date code: 1942)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and



post change parts.

## **Time Table Summary:**

	April 2019			->	September 2019			October 2019							
Workweek	14	15	16	17	18		36	37	38	39	40	41	42	43	44
Initial PCN Issue Date			Χ												
Qual Report Availability								Χ							
Final PCN Issue Date								Χ							
Estimated Implementation Date													Χ		

## **Method to Identify Change:**

Traceability code

## **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

## **Revision History**:

April 17, 2019: Issued initial notification.

**September 13, 2019:** Issued final notification. Attached the qualification report. Provided estimated first date to be on October 13, 2019

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachment(s):

PCN\_RMES-16DZWG089\_Qual\_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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### Affected Catalog Part Numbers (CPN)

MCP33111-05-E/MS

MCP33111-05T-E/MS

MCP33111-10-E/MS

MCP33111-10T-E/MS

MCP33111D-05-E/MS

MCP33111D-05T-E/MS

MCP33111D-10-E/MS

MCP33111D-10-I/MS

MCP33111D-10T-E/MS

MCP33111D-10T-I/MS

MCP33121-05-E/MS

MCP33121-05T-E/MS

MCP33121-10-E/MS

MCP33121-10T-E/MS

MCP33121D-05-E/MS

MCP33121D-05T-E/MS

MCP33121D-10-E/MS

MCP33121D-10-I/MS

MCP33121D-10T-E/MS

MCP33121D-10T-I/MS

MCP33131-05-E/MS

MCP33131-05T-E/MS

MCP33131-10-E/MS

MCP33131-10T-E/MS

MCP33131D-05-E/MS

MCP33131D-05T-E/MS

MCP33131D-10-E/MS

MCP33131D-10-I/MS

MCP33131D-10T-E/MS

MCP33131D-10T-I/MS

Date: Thursday, September 12, 2019